

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V _F	Diode Forward Voltage	I _F = 400A	T _j = 25°C		2.2	2.5	V
			T _j = 125°C		2.1		
I _{RM}	Maximum Reverse Leakage Current	V _R = 1700V	T _j = 25°C			750	μA
			T _j = 125°C			1000	

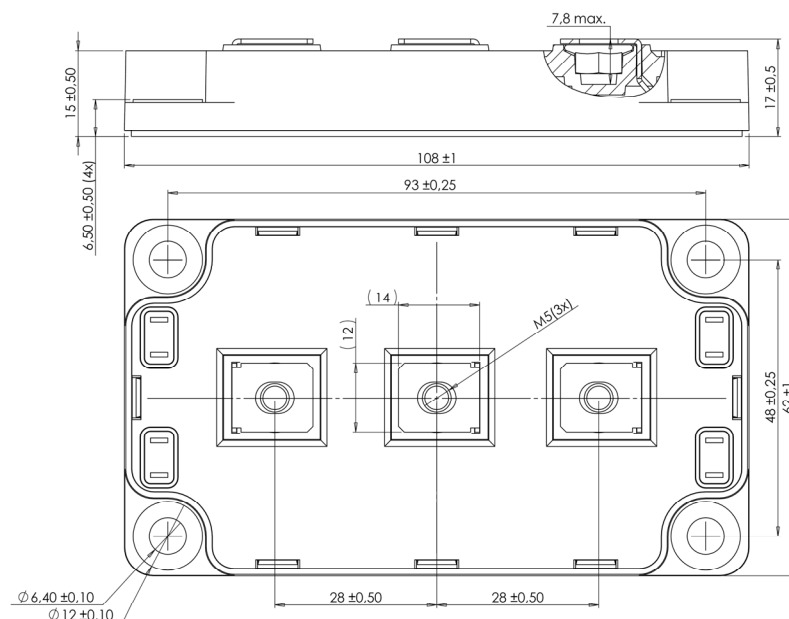
Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time	I _F = 400A V _R = 900V di/dt = 4000A/μs	T _j = 25°C		572		ns
			T _j = 125°C		704		
Q _{rr}	Reverse Recovery Charge		T _j = 25°C		80		μC
			T _j = 125°C		140		
I _{RRM}	Reverse Recovery Current		T _j = 25°C		280		A
			T _j = 125°C		400		

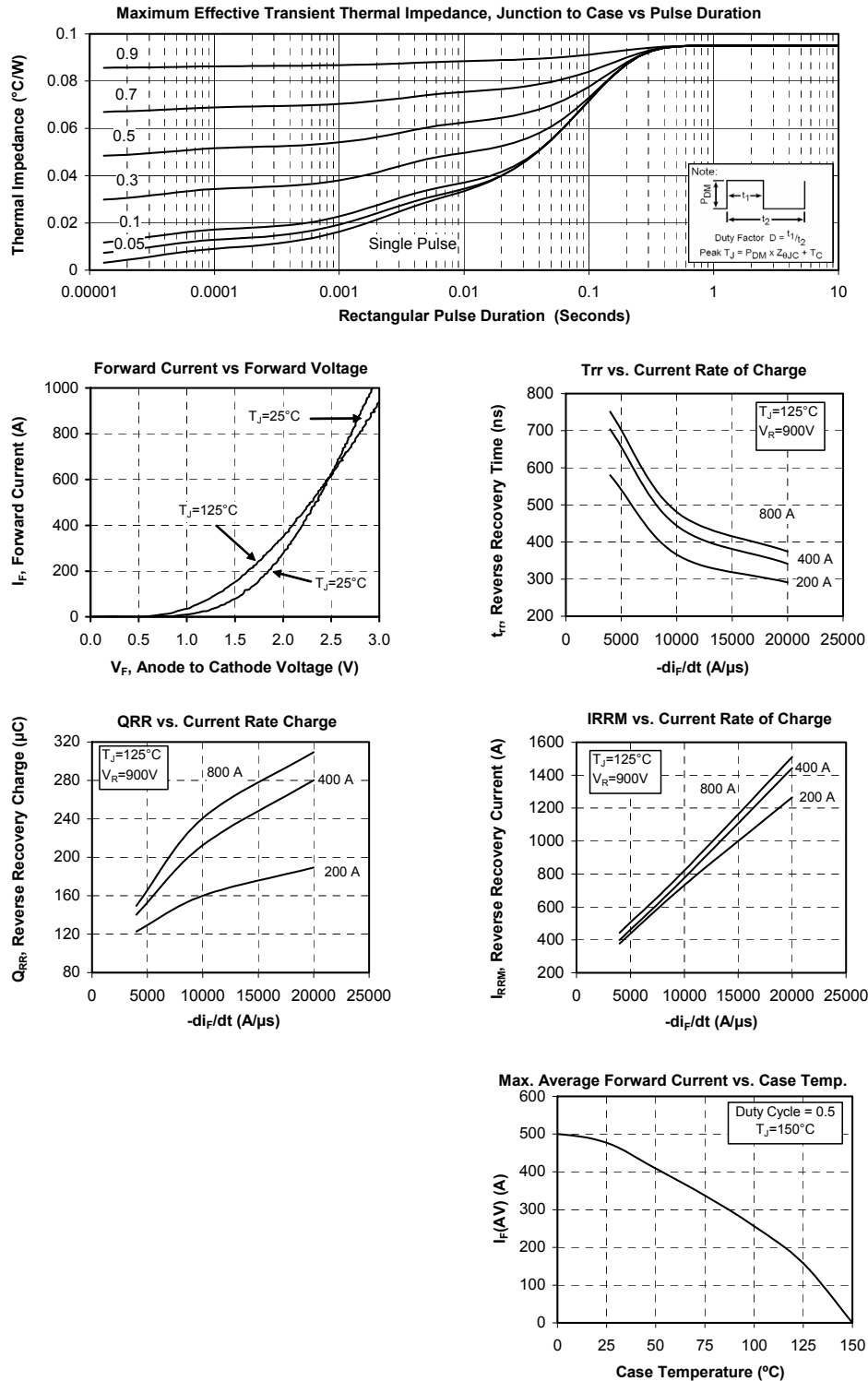
Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance			0.095	$^\circ\text{C}/\text{W}$
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, 50/60Hz	4000			V
T_j	Operating junction temperature range	-40		150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40		125	
T_C	Operating Case Temperature	-40		100	
Torque	Mounting torque	To heatsink	M6	3	N.m
		For terminals	M5	2	
Wt	Package Weight			300	g

SP6 Package outline (dimensions in mm)



Typical Performance Curve



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